



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20220714000.0
Datasheet for SNx4HCT573, SNx4HC563, SNx4HCT273, SNx4HCT373, and SNx4HC540
Information Only

Date: July 25, 2022
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74HCT373N	null

Technical details of this Product Change follow on the next page(s).

Notification Number:	20220714000.0	Notification Date:	July 25, 2022
Title:	Datasheet for SNx4HCT573, SNx4HC563, SNx4HCT273, SNx4HCT373, and SNx4HC540		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheets are being updated to more accurately reflect the thermal characteristics of the devices. Some devices have not been physically changed and are only receiving updated thermal models, while others are changing due to updated physical characteristics. Physical changes to the individual devices were previously notified in PCN # 20210927002. Please refer to the previous PCN to verify which specific devices are affected. The following change history provides further details.



SN54HCT573, SN74HCT573
SCLS176G – JULY 2003 – REVISED JULY 2022

Changes from Revision F (February 2022) to Revision G (July 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8..... 4



SN54HC563, SN74HC563
SCLS145E – DECEMBER 1982 – REVISED JULY 2022

Changes from Revision D (January 2022) to Revision E (July 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6.... 4



SN54HCT273, SN74HCT273
SCLS068G – NOVEMBER 1988 – REVISED JULY 2022

Changes from Revision F (February 2022) to Revision G (July 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, DB was 70 is now 122.7, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8..... 4



SN54HCT373, SN74HCT373
SCLS009F – MARCH 1984 – REVISED JULY 2022

Changes from Revision E (December 2021) to Revision F (July 2022) Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8..... 4

Changes from Revision F (December 2021) to Revision G (July 2022)
Page

- Removed DB package.....4

Changes from Revision E (January 2022) to Revision F (July 2022)
Page

- Junction-to-ambient thermal resistance values increased. DW was 58 is now 109.1, N was 69 is now 84.6, NS was 60 is now 113.4, PW was 83 is now 131.8.....4

The datasheet number will be changing.

Device Family	Change From:	Change To:
SNx4HCT573	SCLS176F	SCLS176G
SNx4HC563	SCLS145D	SCLS145E
SNx4HCT273	SCLS068F	SCLS068G
SNx4HCT373	SCLS009E	SCLS009G
SNx4HC540	SCLS007E	SCLS007F

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/SN54HCT573>

<https://www.ti.com/product/SN54HC563>

<https://www.ti.com/product/SN54HCT273>

<https://www.ti.com/product/SN54HCT373>

<https://www.ti.com/product/SN54HC540>

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. There are no changes to the actual device for this document update.

Changes to product identification resulting from this notification:

None.

Product Affected:

SN74HC540DW	SN74HC563DW	SN74HCT273PW	SN74HCT373PWT
SN74HC540DWE4	SN74HC563DWR	SN74HCT273PWR	SN74HCT573DBR
SN74HC540DWG4	SN74HC563N	SN74HCT273PWT	SN74HCT573DBRG4
SN74HC540DWR	SN74HC563NS	SN74HCT373DW	SN74HCT573DW
SN74HC540N	SN74HCT273DBR	SN74HCT373DWR	SN74HCT573DWR
SN74HC540NS	SN74HCT273DW	SN74HCT373DWRE4	SN74HCT573DWRG4
SN74HC540NSR	SN74HCT273DWR	SN74HCT373N	SN74HCT573N
SN74HC540PW	SN74HCT273DWRG4	SN74HCT373NE4	SN74HCT573NS

SN74HC540PWR	SN74HCT273N	SN74HCT373NSR	SN74HCT573NSR
SN74HC540PWRE4	SN74HCT273NS	SN74HCT373PW	SN74HCT573PW
SN74HC540PWT	SN74HCT273NSR	SN74HCT373PWR	SN74HCT573PWR

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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